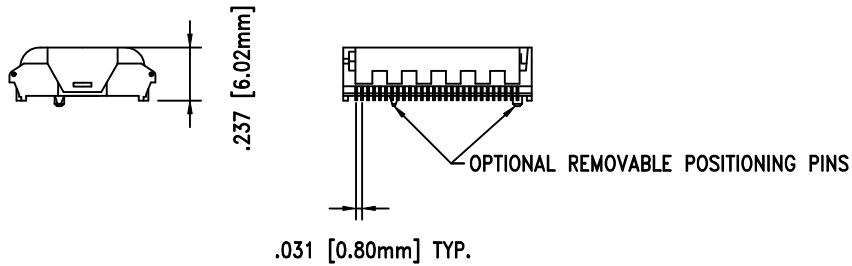
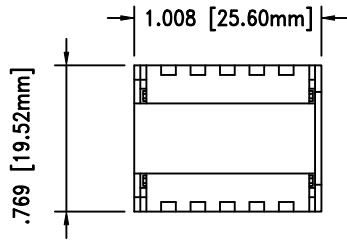
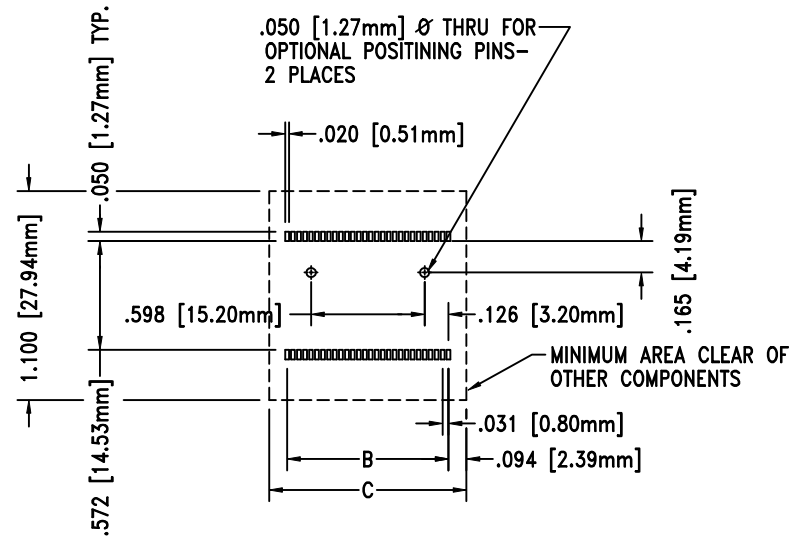


REV	DESCRIPTION	DATE
A	NEW DRAWING	7/7/95
B	UPDATED DRAWING	2/29/01

SKT517
DOD 4517



DIM B		DIM C	
mm	inches	mm	inches
21.60	.850	27.38	1.078



SOCKET LAND-PAD FOOTPRINT

SPECIFICATIONS:

- FOR OEM, PROGRAMMING, PROTOTYPING AND TEST APPLICATIONS
- SURFACE MOUNT ZERO-INSERTION FORCE
- LAND-PAD FOOTPRINT COMMON FOR PACKAGE AND SOCKET
- EFFORTLESS PACKAGE LOADING AND UNLOADING
- BODY, LID AND LOCK MATERIAL: LCP
- TERMINAL MATERIAL: BeCu WITH PbSn PLATING
- MINIMUM INSERTION/WITHDRAWAL CYCLES: 30
- TEMPERATURE RANGE: -55 C TO + 105 C
- CURRENT RATING: 0.5 AMP
- FLAMMABILITY: 940V-0

PACKAGE SPECIFICATIONS	
PIN COUNT	= 56
LEAD PITCH	= 0.80mm
PACKAGE WIDTH	= 13.30mm

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



Emulation Technology, Inc.
 — VLSI and SMT ADAPTERS and ACCESSORIES —

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 FAX:(408)982-0664

SHEET: 1 OF 1	DATE: 2/29/01	REVISION: B	ASSEMBLY DRAWING
CHECKED: Perry Munroe	DRAWN: Aaron Fine	ITEM: S-SSO-SM-056-A	DESCRIPTION: S-SSO-SM-056-A
DO NOT SCALE DRAWING			